

CONNECTION METHOD, CIRCUIT BOARD USING THE SAME AND ITS PRODUCING METHOD, SEMICONDUCTOR PACKAGE AND ITS MANUFACTURING METHOD

Publication number: JP2002185097 (A)

Publication date: 2002-06-28

Inventor(s): NAKAMURA HIDEHIRO; ENDO TOSHIHIRO; ENOMOTO TETSUYA; INOUE FUMIO; TSUBOMATSU YOSHIAKI; NAKASO AKISHI

Applicant(s): HITACHI CHEMICAL CO LTD

Classification:

- international: *C08K3/00; C08L101/00; H01L23/12; H05K1/11; H05K3/00; H05K3/42; C08K3/00; C08L101/00; C08K3/00; C08L101/00; H01L23/12; H05K1/11; H05K3/00; H05K3/42; C08K3/00; C08L101/00; (IPC1-7): C08K3/00; C08L101/00; H05K1/11; H01L23/12; H05K3/00; H05K3/42*

- European:

Application number: JP20000377478 20001212

Priority number(s): JP20000377478 20001212

Abstract of **JP 2002185097 (A)**

PROBLEM TO BE SOLVED: To provide a connecting method exhibiting proper accuracy and efficiency, a circuit board using that method, a semiconductor package, and to provide its manufacturing method. SOLUTION: In the method for connecting a conductor buried in an insulating resin with a conductor on the surface of the insulating resin, an opening is made by removing the surface conductor from a part where the interval between the embedded conductor and the surface conductor is 50 μm or less, the insulating resin exposed to the opening is removed, and then the buried conductor is connected with the surface conductor through plating. The buried conductor is used in a circuit board for connecting the surface conductor with an outer layer conductor formed on the insulating resin layer opposite to the surface conductor.; A method for producing the circuit board, a semiconductor package and its manufacturing method, are also provided.

.....
Data supplied from the *esp@cenet* database — Worldwide